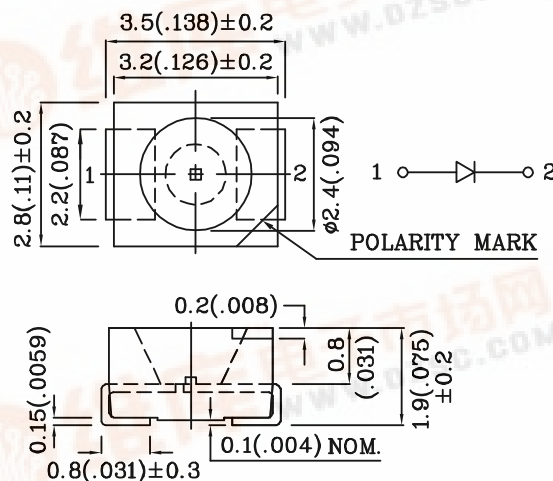


Features

- SINGLE COLOR.
- SUITABLE FOR ALL SMT ASSEMBLY AND SOLDER PROCESS.
- AVAILABLE ON TAPE AND REEL.
- IDEAL FOR BACKLIGHTING.
- PACKAGE : 1500PCS / REEL.
- RoHS COMPLIANT.



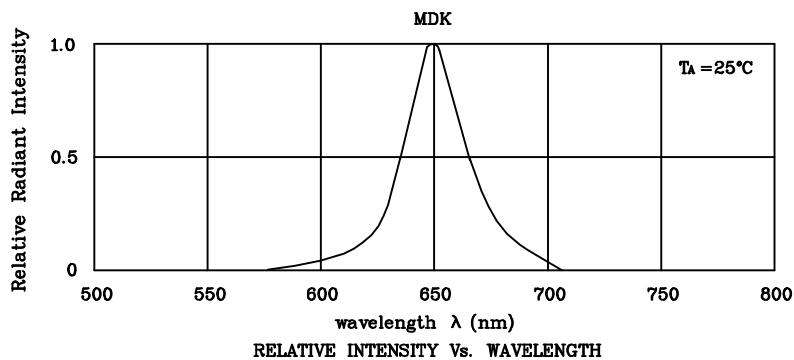
Notes:

1. All dimensions are in millimeters (inches).
2. Tolerance is $\pm 0.25(0.01")$ unless otherwise noted.

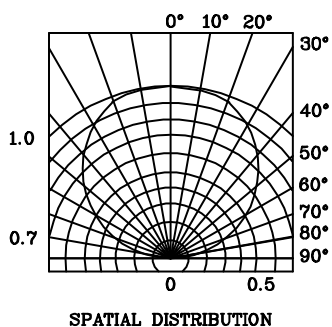
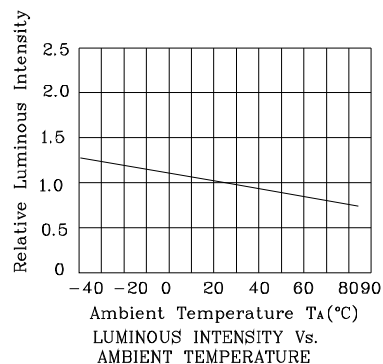
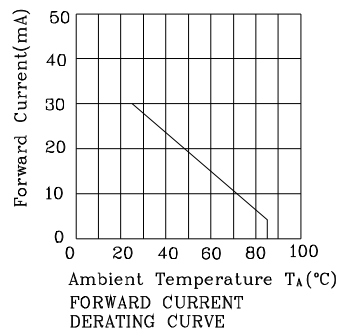
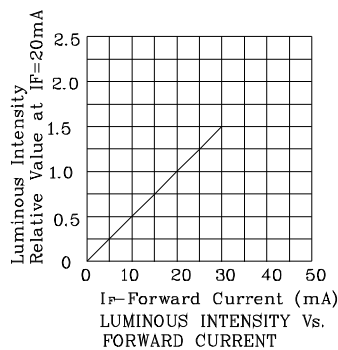
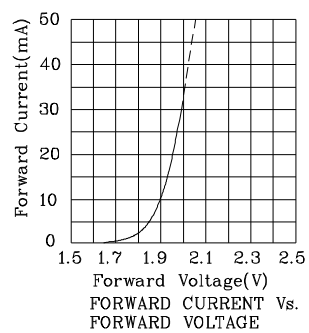
Absolute maximum ratings (TA=25°C)		MDK (InGaAlP)	Unit
Reverse voltage	VR	5	V
Forward current	IF	30	mA
Forward current (peak) 1/10Duty cycle 0.1ms pulse width	iFS	185	mA
Power dissipation	PT	75	mW
Operating temperature	TA	-40 ~ +85	°C
Storage temperature	Tstg	-40 ~ +85	

Operating Characteristics (T _A =25°C)		MDK (InGaAlP)	Unit
Forward voltage (typ.) (I _F =20mA)	V _F	1.95	V
Forward voltage (max.) (I _F =20mA)	V _F	2.5	V
Reverse current (V _R =5V)	I _R	10	uA
Wavelength at peak emission (I _F =20mA)	λ peak	650	nm
Wavelength of Dominant emission (I _F =20mA)	λ D	635	nm
Spectral Line half-width (I _F =20mA)	Δλ	28	nm
Capacitance (V _F =0V, f=1MHz)	C	35	pF

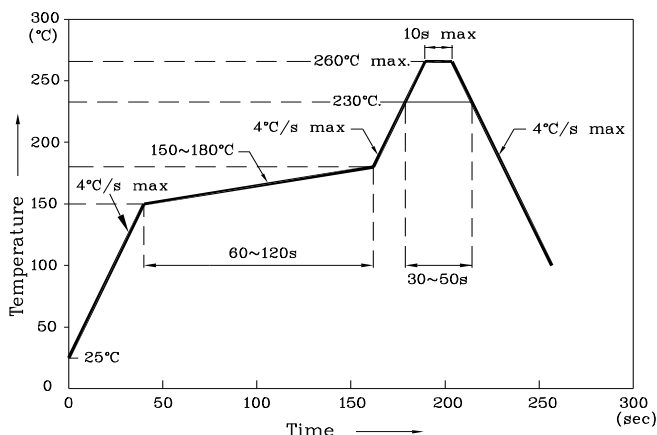
Part Number	Emitting Color	Emitting Material	Lens-color	Luminous Intensity (IF=20mA) mcd	Wavelength nm λ P	Viewing Angle 2 θ 1/2
ZMDK 45W	Red	InGaAlP	Water Clear	70	650	120°



❖ **MDK**



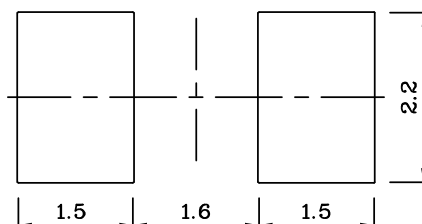
Reflow Soldering Profile For Lead-free SMT Process.



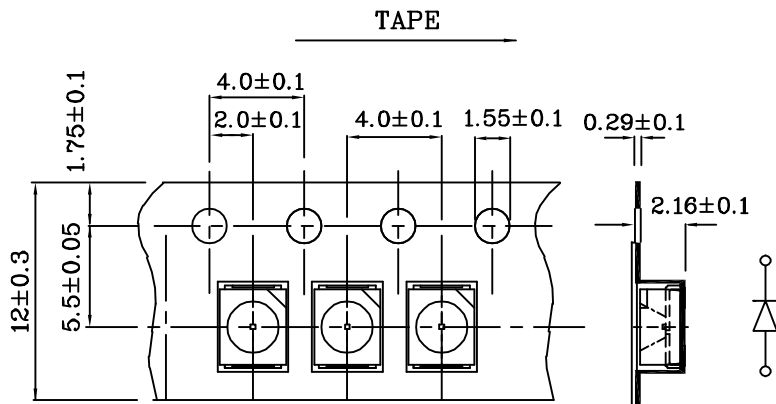
Notes:

1. Maximum soldering temperature should not exceed 260°C.
2. Recommended reflow temperature: 145°C–260°C.
3. Do not put stress to the epoxy resin during high temperatures conditions.

❖ Recommended Soldering Pattern (Units : mm;Tolerance:±0.1)



❖ Tape Specification (Units : mm)



If special sorting is required (e.g. binning based on forward voltage, luminous intensity, or wavelength), the typical accuracy of the sorting process is as follows:

1. Wavelength: +/-1nm
2. Luminous Intensity: +/-15%
3. Forward Voltage: +/-0.1V

Note: Accuracy may depend on the sorting parameters.